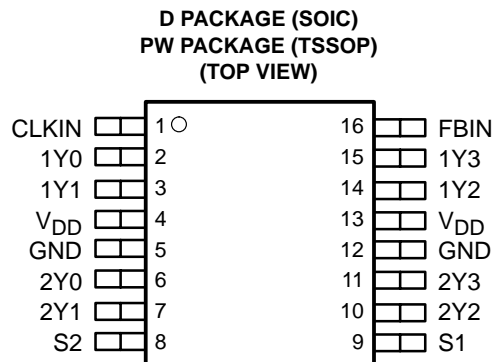- **Phase-Locked Loop-Based Zero-Delay Buffer**
- **Operating Frequency: 10 MHz to 200 MHz**
- **Low Jitter (Cycle-Cycle): ±100 ps Over the Range 66 MHz to 200 MHz**
- **Distributes One Clock Input to Two Banks of Four Outputs**
- **Auto Frequency Detection to Disable Device (Power Down Mode)**
- **Consumes Less Than 20 μA in Power Down Mode**
- **Operates From Single 3.3-V Supply**
- **Industrial Temperature Range –40°C to 85°C**
- **25-Ω On-Chip Series Damping Resistors**
- **No External RC Network Required**
- **Spread Spectrum Clock Compatible (SSC)**
- **Available in 16-Pin TSSOP or 16-Pin SOIC Packages**

D PACKAGE (SOIC)
PW PACKAGE (TSSOP)
(TOP VIEW)

CLKIN	1	16 FBIN
1Y0	2	15 1Y3
1Y1	3	14 1Y2
V_DD	4	13 V_DD
GND	5	12 GND
2Y0	6	11 2Y3
2Y1	7	10 2Y2
S2	8	9 S1

description

The CDCVF25081 is a high-performance, low-skew, low-jitter, phase-lock loop clock driver. It uses a PLL to precisely align, in both frequency and phase, the output clocks to the input clock signal. The CDCVF25081 operates from a nominal supply voltage of 3.3 V. The device also includes integrated series-damping resistors in the output drivers that make it ideal for driving point-to-point loads.

Two banks of four outputs each provide low-skew, low-jitter copies of CLKIN. All outputs operate at the same frequency. Output duty cycles are adjusted to 50%, independent of duty cycle at CLKIN. The device automatically goes into power-down mode when no input signal is applied to CLKIN and the outputs go into a low state. Unlike many products containing PLLs, the CDCVF25081 does not require an external RC network. The loop filter for the PLL is included on-chip, minimizing component count, space, and cost.

Because it is based on a PLL circuitry, the CDCVF25081 requires a stabilization time to achieve phase lock of the feedback signal to the reference signal. This stabilization is required following power up and application of a fixed-frequency signal at CLKIN and any following changes to the PLL reference.

The CDCVF25081 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE

S2	S1	1Y0–1Y3	2Y0–2Y3	OUTPUT SOURCE	PLL SHUTDOWN
0	0	Hi-Z	Hi-Z	N/A.	Yes
0	1	Active	Hi-Z	PLL†	No
1	0	Active	Active	Input clock (PLL bypass)	Yes
1	1	Active	Active	PLL†	No

† CLK input frequency < 2 MHz switches the outputs to low level

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TEXAS INSTRUMENTS

Terminal Functions

TERMINAL		TYPE	DESCRIPTION
NAME	PIN NO.		
1Y[0:3]	2, 3, 14, 15	O	Bank 1Yn clock outputs. These outputs are low-skew copies of CLKIN. Each output has an integrated 25-Ω series-damping resistor.
2Y[0:3]	6, 7, 10, 11	O	Bank 2Yn clock outputs. These outputs are low-skew copies of CLKIN. Each output has an integrated 25-Ω series-damping resistor.
CLKIN	1	I	Clock input. CLKIN provides the clock signal to be distributed by the CDCVF25081 clock driver. CLKIN is used to provide the reference signal to the integrated PLL that generates the output signal. CLKIN must have a fixed frequency and phase in order for the PLL to acquire lock. Once the circuit is powered up and a valid signal is applied, a stabilization time is required for the PLL to phase lock the feedback signal to CLKIN.
FBIN	16	I	Feedback input. FBIN provides the feedback signal to the internal PLL. FBIN must be wired to one of the outputs to complete the feedback loop of the internal PLL. The integrated PLL synchronizes the FBIN and output signal so there is nominally zero-delay from input clock to output clock.
GND	5, 12	Ground	Ground
S1, S2	9, 8	I	Select pins to determine mode of operation. See the *FUNCTION TABLE* for mode selection options.
V$_{DD}$	4, 13	Power	Supply voltage. The supply voltage range is 3 V to 3.6 V

functional block diagram
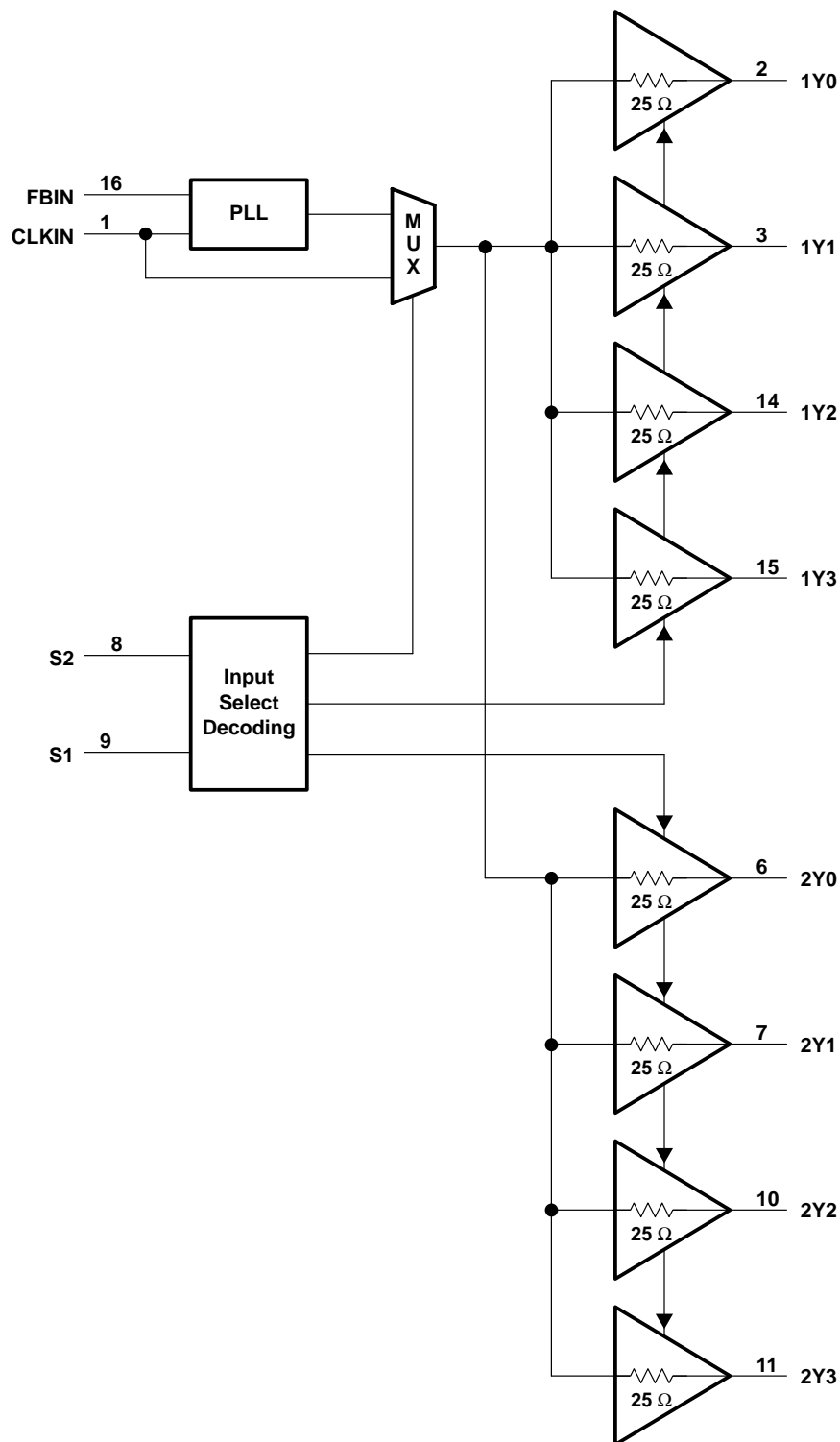
absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage range, V_{DD} .... –0.5 V to 4.6 V
Input voltage range, V_I (see Notes 1 and 2) .... –0.5 V to 4.6 V
Output voltage range, V_O (see Notes 1 and 2) .... –0.5 V to V_{DD} + 0.5 V
Input clamp current, I_{IK} (V_I < 0) .... –50 mA
Output clamp current, I_{OK} (V_O < 0) .... –50 mA
Continuous total output current, I_O (V_O = 0 to V_{DD}) .... –50 mA
Package thermal impedance, θ_{JA} (see Note 3): PW package .... 147°C/W
                                                           D package .... 112°C/W
Storage temperature range, T_{stg} .... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and
  functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not
  implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
            2. This value is limited to 4.6 V maximum.
            3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{DD}	3	3.3	3.6	V
Low level input voltage, V_{IL}			0.8	V
High level input voltage, V_{IH}	2			V
Input voltage, V_I	0		3.6	V
High-level output current, I_{OH}			–12	mA
Low-level output current, I_{OL}			12	mA
Operating free-air temperature, T_A	-40		85	°C

timing requirements over recommended ranges of supply voltage, load and operating free-air temperature

		MIN	NOM	MAX	UNIT
Clock frequency, f_{clk}	C_L = 25 pF	10		100	MHz
	C_L = 15 pF	66		200	

TEXAS INSTRUMENTS

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP[†]	MAX	UNIT
V_{IK}	Input voltage	$V_{DD} = 3$ V,	$I_I = -18$ mA			−1.2	V
I_I	Input current	$V_I = 0$ V or V_{DD}				±5	µA
I_{PD}[‡]	Power down current	$f_{CLKIN} = 0$ MHz,	$V_{DD} = 3.3$ V			20	µA
I_{OZ}	Output 3-state	$V_O = 0$ V or V_{DD},	$V_{DD} = 3.6$ V			±5	µA
C_I	Input capacitance at FBIN, CLKIN	$V_I = 0$ V or V_{DD}			4		pF
C_I	Input capacitance at S1, S2	$V_I = 0$ V or V_{DD}			2.2		pF
C_O	Output capacitance	$V_I = 0$ V or V_{DD}			3		pF
V_{OH}	High-level output voltage	V_{DD} = min to max,	$I_{OH} = -100$ µA	$V_{DD} - 0.2$			V
		$V_{DD} = 3$ V,	$I_{OH} = -12$ mA	2.1			
		$V_{DD} = 3$ V,	$I_{OH} = -6$ mA	2.4			
V_{OL}	Low-level output voltage	V_{DD} = min to max,	$I_{OL} = 100$ µA			0.2	V
		$V_{DD} = 3$ V,	$I_{OL} = 12$ mA			0.8	
		$V_{DD} = 3$ V,	$I_{OL} = 6$ mA			0.55	
I_{OH}	High-level output current	$V_{DD} = 3$ V,	$V_O = 1$ V	−24			mA
		$V_{DD} = 3.3$ V,	$V_O = 1.65$ V		−30		
		$V_{DD} = 3.6$ V,	$V_O = 3.135$ V			-15	
I_{OL}	Low-level output current	$V_{DD} = 3$ V,	$V_O = 1.95$ V	26			mA
		$V_{DD} = 3.3$ V,	$V_O = 1.65$ V		33		
		$V_{DD} = 3.6$ V,	$V_O = 0.4$ V			14	

[†] All typical values are at respective nominal V_{DD}.
[‡] For I_{DD} over frequency see Figure 7.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted)

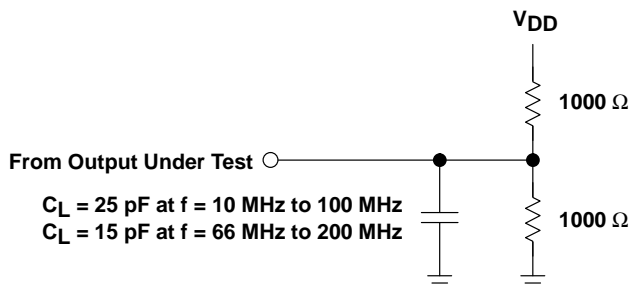| PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
$t_{(lock)}$	PLL lock time	f = 100 MHz		10		µs
$t_{(phoffset)}$	Phase offset (CLKIN to FBIN)	f = 10 MHz to 66 MHz, Vth = V_{DD}/2 (see Note 5)	−200		200	ps
		f = 66 MHz to 200 MHz, Vth = V_{DD}/2 (see Note 5)	−150		150	
t_{PLH}	Low-to-high level output propagation delay	S2 = High, S1 = Low (PLL bypass) f = 1 MHz, C_L = 25 pF	2.5		6	ns
t_{PHL}	High-to-low level output propagation delay					
$t_{sk(o)}$	Output skew (Yn to Yn) (see Note 4)				150	ps
$t_{sk(pp)}$	Part-to-part skew	S2 = high, S1 = high (PLL mode)			600	ps
		S2 = high, S1 = low (PLL bypass)			700	
$t_{jit(cc)}$	Jitter (cycle-to-cycle)	f = 66 MHz to 200 MHz, C_L = 15 pF			±100	ps
		f = 66 MHz to 100 MHz, C_L = 25 pF f = 10 MHz to 66 MHz (see Figure 6)			±150	
odc	Output duty cycle	f = 10 MHz to 200 MHz	43%		57%	
$t_{sk(p)}$	Pulse skew	S2 = High, S1 = low (PLL bypass) f = 1 MHz, C_L = 25 pF			0.7	ns
t_r	Rise time rate	C_L = 15 pF, See Figure 4	0.8		3.3	V/ns
		C_L = 25 pF, See Figure 4	0.5		2	
t_f	Fall time rate	C_L = 15 pF, See Figure 4	0.8		3.3	V/ns
		C_L = 25 pF, See Figure 4	0.5		2	

† All typical values are at respective nominal V_{DD}.

NOTES: 4. The $t_{sk(o)}$ specification is only valid for equal loading of all outputs.

5. Similar waveform at CLKIN and FBIN are required. For phase displacement between CLKIN and Y-outputs see Figure 5.

PARAMETER MEASUREMENT INFORMATION

V_{DD}

1000 Ω

From Output Under Test

C_L = 25 pF at f = 10 MHz to 100 MHz
C_L = 15 pF at f = 66 MHz to 200 MHz

1000 Ω

NOTES: A. C_L includes probe and jig capacitance.
      B. All input pulses are supplied by generators having the following characteristics: $Z_O = 50\ \Omega$, $t_r < 1.2$ ns, $t_f < 1.2$ ns.
      C. The outputs are measured one at a time with one transition per measurement.
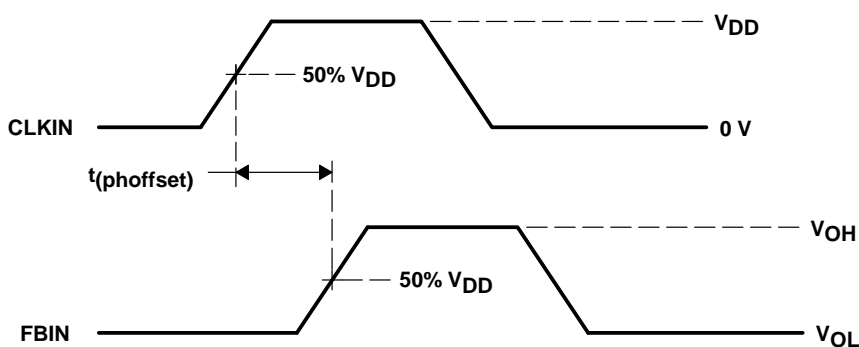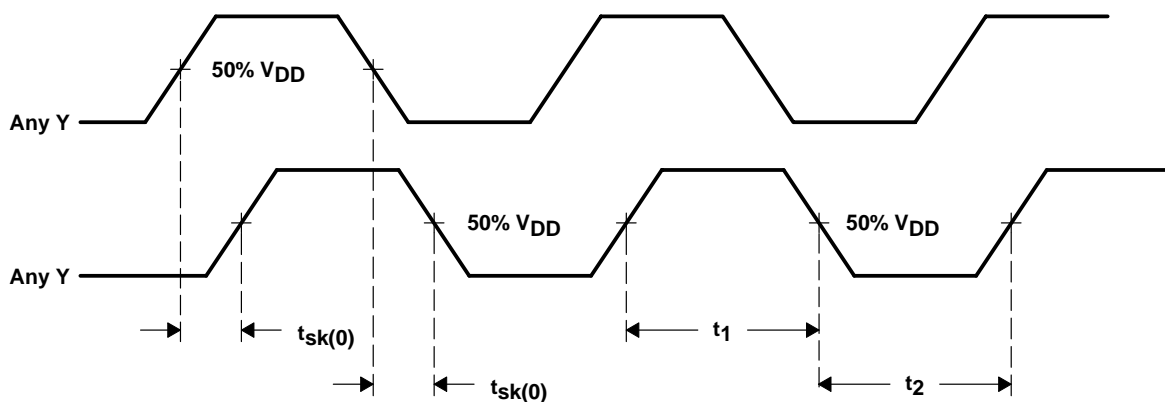
Figure 1. Test Load Circuit

Figure 2. Voltage Thresholds for Measurements, Phase Offset (PLL Mode)
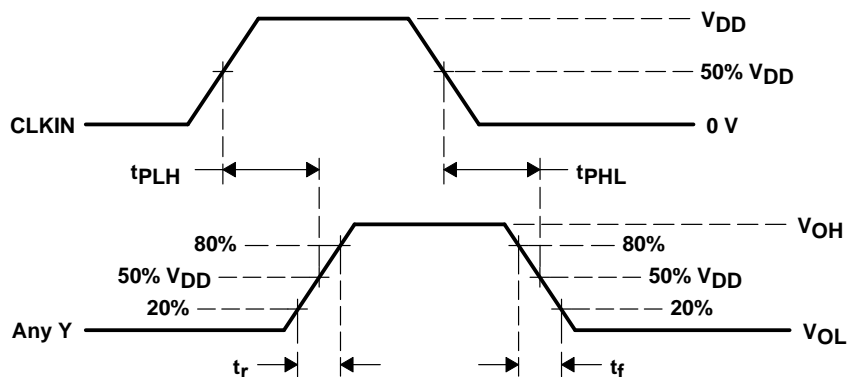
NOTE: odc = $t_1/(t_1 + t_2)$ x 100%

Figure 3. Output Skew and Output Duty Cycle (PLL Mode)

PARAMETER MEASUREMENT INFORMATION

NOTE: $t_{sk(p)} = |t_{PLH} - t_{PHL}|$

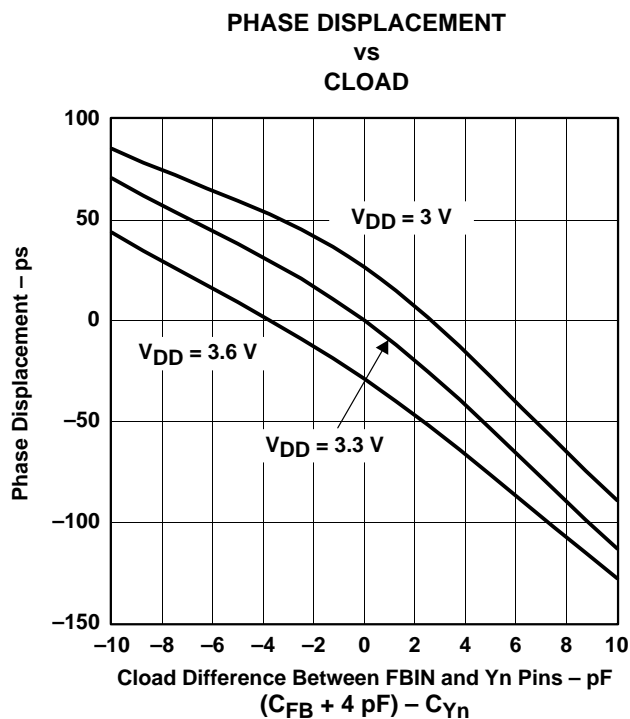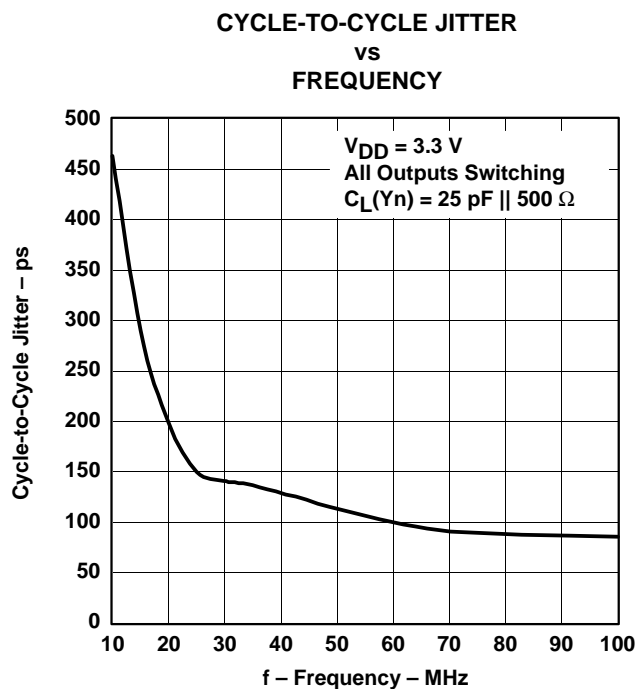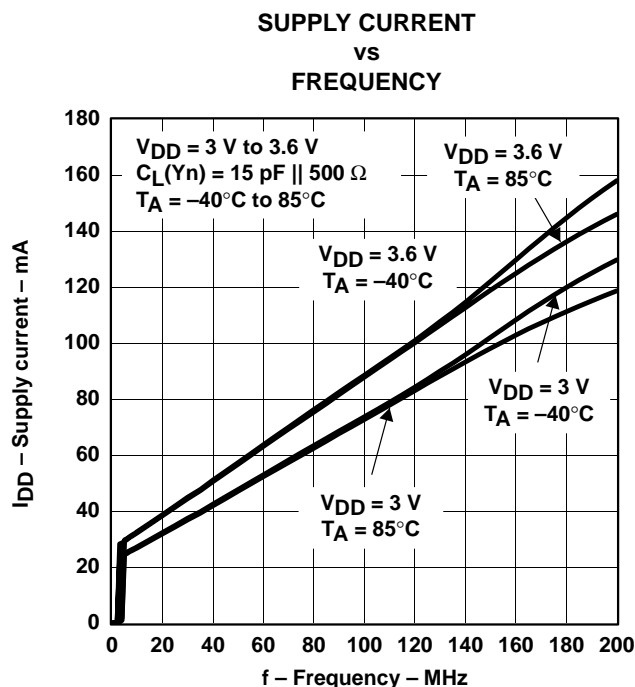**Figure 4. Propagation Delay and Pulse Skew (Non-PLL Mode)**

**PHASE DISPLACEMENT
vs
CLOAD**

**CYCLE-TO-CYCLE JITTER
vs
FREQUENCY**

Figure 5

Figure 6

PARAMETER MEASUREMENT INFORMATION

SUPPLY CURRENT
vs
FREQUENCY

V_{DD} = 3 V to 3.6 V
C_L(Yn) = 15 pF || 500 Ω
T_A = −40°C to 85°C

V_{DD} = 3.6 V
T_A = 85°C

V_{DD} = 3.6 V
T_A = −40°C

V_{DD} = 3 V
T_A = −40°C

V_{DD} = 3 V
T_A = 85°C

I_{DD} – Supply current – mA

f – Frequency – MHz

Figure 7

MECHANICAL DATA

PW (R-PDSO-G)**   **PLASTIC SMALL-OUTLINE PACKAGE**

14 PINS SHOWN
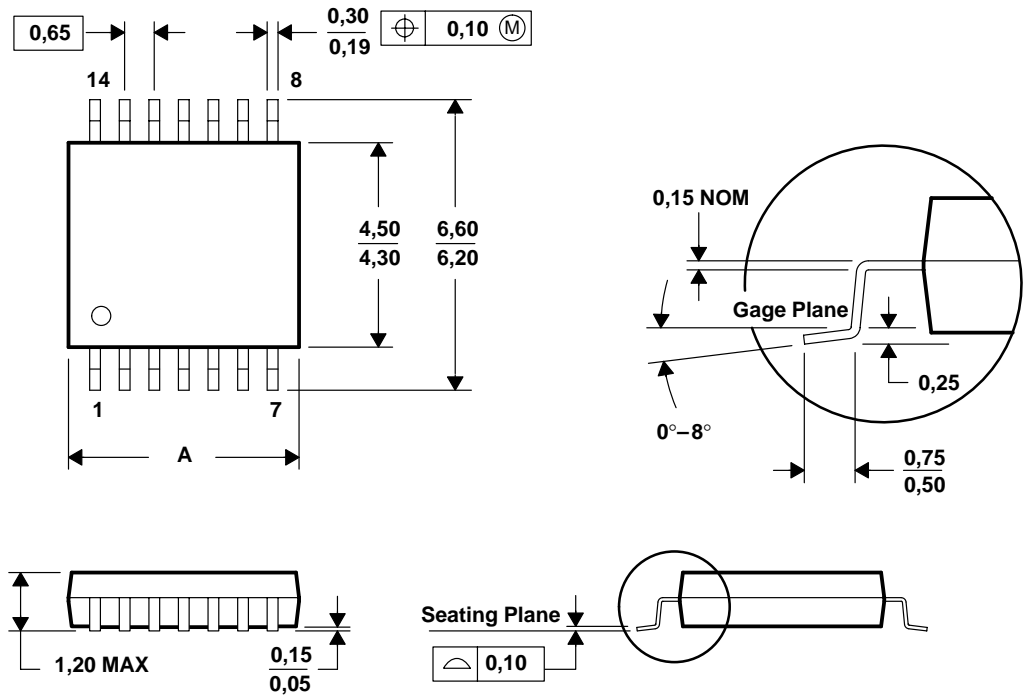
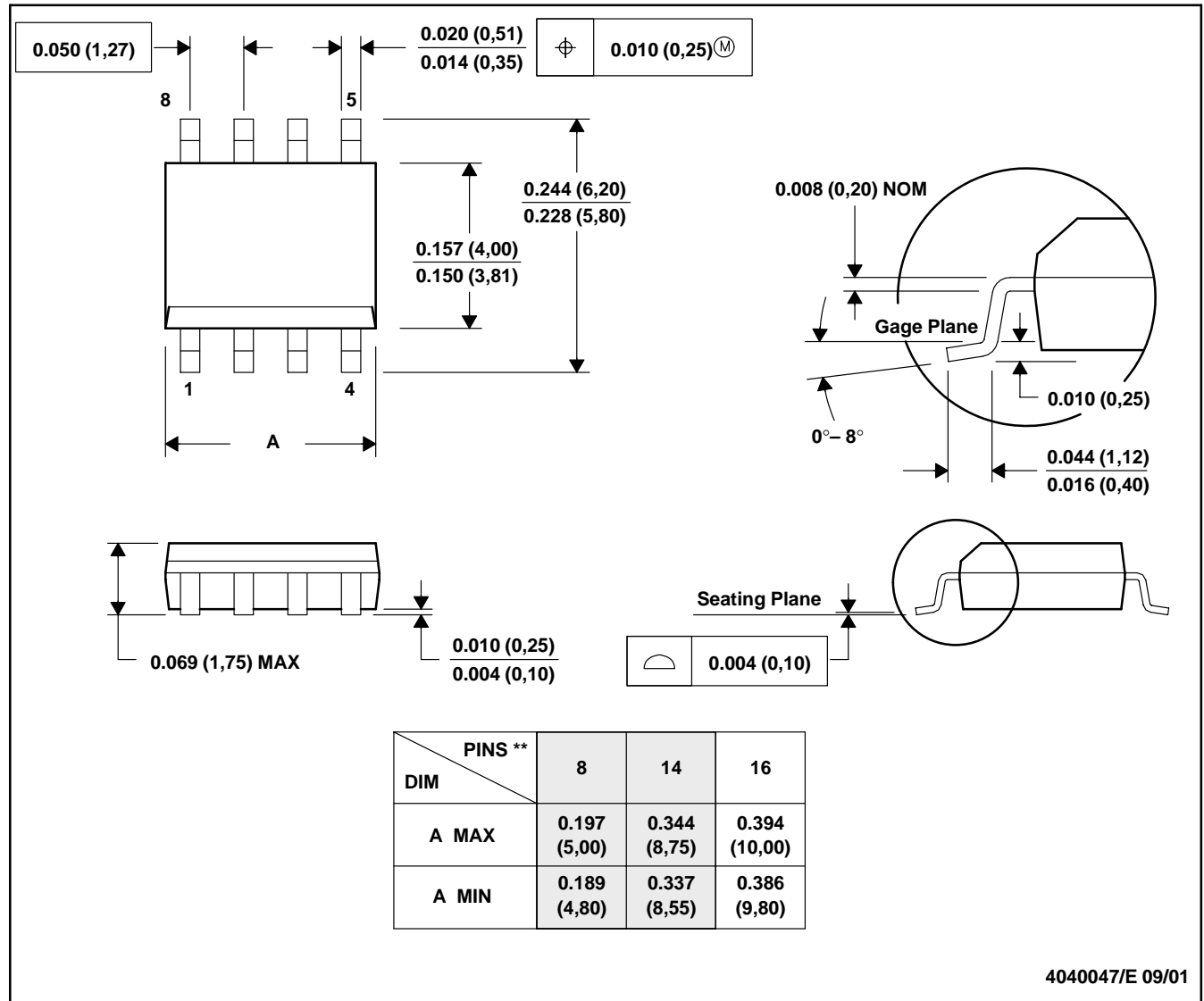| DIM / PINS **	8	14	16	20	24	28
A MAX	3,10	5,10	5,10	6,60	7,90	9,80
A MIN	2,90	4,90	4,90	6,40	7,70	9,60

4040064/F 01/97

NOTES: A. All linear dimensions are in millimeters.
           B. This drawing is subject to change without notice.
           C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
           D. Falls within JEDEC MO-153

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MECHANICAL DATA

D (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE PACKAGE**

8 PINS SHOWN

PINS ** / DIM	8	14	16
A MAX	0.197 (5,00)	0.344 (8,75)	0.394 (10,00)
A MIN	0.189 (4,80)	0.337 (8,55)	0.386 (9,80)

4040047/E 09/01

NOTES: A. All linear dimensions are in inches (millimeters).
        B. This drawing is subject to change without notice.
        C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
        D. Falls within JEDEC MS-012

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Mailing Address:

Texas Instruments
Post Office Box 655303
Dallas, Texas 75265